



Material Composition Sheet

Product: GS1575ACNE3
 Package Type: QFN-64 pin (260/tray)
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Die		7.25	Al	0.04	0.55	5517
			Si	7.21	99.44	994483
			Sub-total:	7.25	99.99	1000000
Die Attach	CRM1076DS	0.68	Ag	0.51	75.00	750000
			Epoxy Resin	0.09	13.23	132353
			Epoxy Silane	0.01	1.47	14706
			Phenol Resin	0.02	2.94	29412
			t-Butylphenylglycidil ether	0.05	7.35	73529
			Sub-total:	0.68	99.99	1000000
Internal Pad Plating		0.23	Ag	0.23	100.00	1000000
			Sub-total:	0.23	100.00	1000000
Leadframe	OLIN 7025	117.14	Cu	112.69	96.20	962011
			Mg	0.18	0.15	1537
			Ni	3.51	2.99	29964
			Si	0.76	0.64	6488
			Sub-total:	117.14	99.98	1000000
Mold Compound	EME G770HC	102.55	Carbon Black	0.21	0.20	2048
			Epoxy Resin	4.92	4.79	47977
			Phenol Resin	4.10	3.99	39980
			Silica Fused	93.32	90.99	909995
			Sub-total:	102.55	99.97	1000000
Terminals Finish		5.26	Sn	5.26	100.00	1000000
			Sub-total:	5.26	100.00	1000000
Wires	AW88	1.78	Au	1.78	100.00	1000000
			Sub-total:	1.78	100.00	1000000
Total:		234.89				

GENNUM CORPORATION

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